Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1412-02**

DATE: **December 23, 2014**

Product Affected: PBGA-256, 313, 376
TEPBGA-420, 480
(Refer Attachment II for affected part#)

Date Effective: **March 23, 2015**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
- ■ Back Mark
- ☐ Date Code
- ☐ Other

Assembly lot marked on the device provides traceability to the material used

Contact: IDT PCN DESK

E-mail: pcndesk@idt.com

Attachment: ■ Yes ☐ No

Samples: Contact your local sales representative for sample and datasheet requests.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ■ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ☐ Other

This notification is to inform our customers that IDT is converting to a new mold compound, Hitachi CEL-9750ZHF10AKL.

There is no change in the moisture sensitivity level (MSL).

Attachment I: Details of change.
Attachment II: Affected part list.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality or reliability performance. Refer to attachments for Qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 90 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: ______________________

☐ ***Approval for shipments prior to effective date.***

Name/Date: ______________________

E-Mail Address: ______________________

Title: ______________________

Phone# /Fax# : ______________________

CUSTOMER COMMENTS: ______________________

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: ______________________

DATE: ______________________

ATTACHMENT I - PCN # : A1412-02

PCN Type: Assembly Material

Data Sheet Change: None

Details Of Change: This notification is to inform our customers that IDT is converting to a new mold compound, Hitachi CEL-9750ZHF10AKL.

There is no change in the moisture sensitivity level (MSL).

You may contact your local sales representative to acknowledge this PCN and request samples.

Description	Changes	
	From	To
Mold Compound	Hitachi CEL-9750HF10F	Hitachi CEL-9750ZHF10AKL

Qualification Test Plan and Results:

Test Vehicle: TEPBGA-480 (2 lots) and PBGA-313 (1 lot)

		Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* Highly Accelerated Stress Test (Unbiased, 130°C/85% RH, 96Hrs)	JESD22-A118	30/0	30/0	30/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	30/0	30/0	30/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	30/0	30/0	30/0
Ball Shear Test	JESD22-B116	5/0	5/0	5/0
X-ray Examination	IDT Spec. MAC-3012 (Package voids, Die attach voids and Wire sweep)	45/0	45/0	45/0

Note:
* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test

ATTACHMENT II - PCN # : A1412-02

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
CA91C142D-25EE	CA91L750-100ILV	CA91L8260B-100IEV	TSI350A-66CLV
CA91C142D-33CE	CA91L8200B-100CE	CA91L862A-50IE	TSI384-133IL
CA91C142D-33CEV	CA91L8200B-100IE	CA91L862A-50IEV	TSI384-133ILV
CA91C142D-33IE	CA91L8260B-100CE	CA91L862A-50IL	
CA91C142D-33IEV	CA91L8260B-100CEV	CA91L862A-50ILV	